

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Hung-Chun Chu</td><td>05/12/2008</td></tr><tr><td>Hsi-Feng Lin</td><td>05/12/2008</td></tr><tr><td>Zhi-Houng Pan</td><td>05/12/2008</td></tr></tbody></table>	Name	Execution Date	Hung-Chun Chu	05/12/2008	Hsi-Feng Lin	05/12/2008	Zhi-Houng Pan	05/12/2008	
Name	Execution Date								
Hung-Chun Chu	05/12/2008								
Hsi-Feng Lin	05/12/2008								
Zhi-Houng Pan	05/12/2008								
RECEIVING PARTY DATA									
Name:	ASUSTeK COMPUTER INC.								
Street Address:	4Fl., No. 150, Li-Te Rd., Peitou								
City:	Taipei								
State/Country:	TAIWAN								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12188174</td></tr></tbody></table>	Property Type	Number	Application Number:	12188174					
Property Type	Number								
Application Number:	12188174								
CORRESPONDENCE DATA									
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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ATTORNEY DOCKET NUMBER:	24039-US-PA								
NAME OF SUBMITTER:	Belinda Lee								
Total Attachments: 2 source=24039Assignment#page1.tif source=24039Assignment#page2.tif									

CH 12188174 \$40.00

ASSIGNMENT

WHEREAS,

- | | |
|-------------------|------------------|
| 1. Chu, Hung-Chun | 2. Lin, Hsi-Feng |
| 3. Pan, Zhi-Houng | |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **HEAT DISSIPATION MODULE AND DETACHABLE EXPANSION CARD
USING THE SAME**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, ASUSTeK COMPUTER INC.
of 4Fl., No. 150, Li-Te Rd., Peitou, Taipei, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chu, Hung-Chun
Sole or First Joint Inventor: Chu, Hung-Chun

Date: 2008 / 5 / 12

Signature: Lin, Hsi-Feng
Second Joint Inventor (if any): Lin, Hsi-Feng

Date: 2008 / 5 / 12

Signature: Pan, Zhi-Hong
Third Joint Inventor (if any): Pan, Zhi-Hong

Date: 2008 / 05 / 12